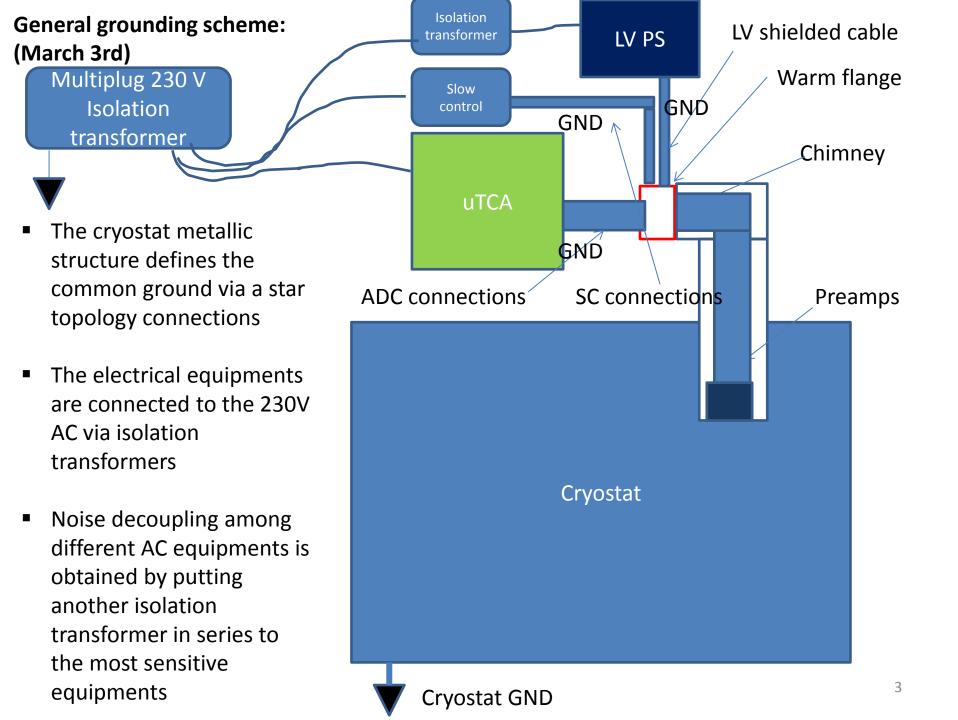
## Front-end tests

2/6/2016

- Extensive discussions on grounding since the end of February with the help of Francois and dedicated meetings (last one on last Friday 27 March)
- → Definition of final grounding scheme being implemented by July 18th based on a common ground at the level of the cryostat and insulation transformers in order to decouple the ground of sensitive equipments
- Checks of all connection scheme from the anode planes to FE cards, chimney flanges, DAQ ADCs
- → Channels mapping, final design and production of FE cards with integration of decoupling and protection components on FE card (R bias, C decoupling and diode pairs) and warm flange (cleaner interface with grounding and shielding, had to be modified anyway since it, half of the pins of each connector were originally set to ground)
- Checks on mechanical compatibility of FE cards
- > Further tests in situ on FE cards insertion and noise checks





#### Fiche e-catalogue

► Accéder à l'accueil e-catalogue

#### REF. 0 428 27



TRANSFO ISOLEMENT TRI PROTÉGÉ - PRIM 400 V/SEC 400 V + N - 16 KVA - ÉCRAN

#### INFORMATION PRODUIT

Découvrez nos solutions sur mesure dans l'onglet logiciel

Tarif unitaire HT	3 490,00 €*
Emballage (nombre d' unité)	1
Volume (dm <sup>3</sup> )	229,00
Poids (kg)	103,00

>> Accéder au e-catalogue pour établir ma liste de matériel >> Accéder au e-catalogue pour imprimer

#### Caractéristiques générales

#### Transformateurs triphasés - IP 21

Cuve RAL 7035

#### Caractéristiques du produit

#### Transformateurs d'isolement

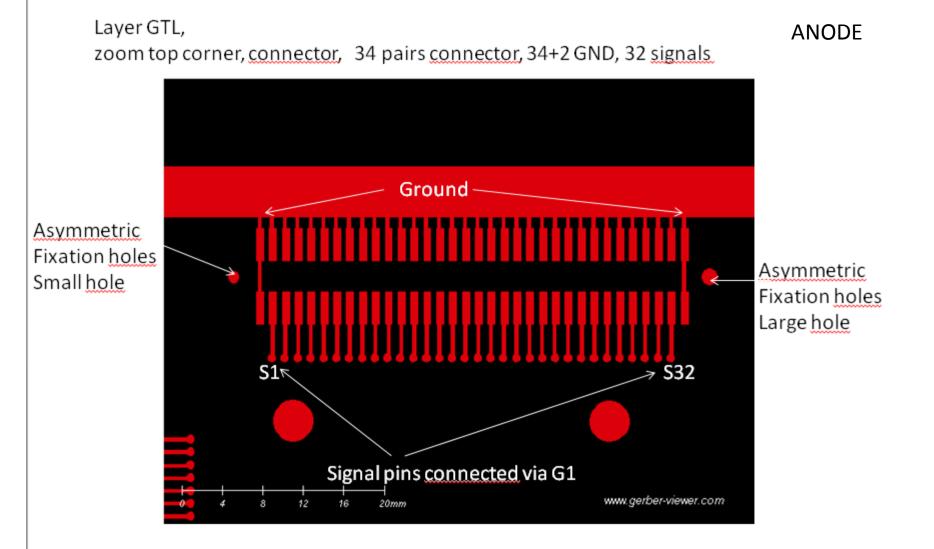
- Conformes à la norme IEC EN 60076-11
- Avec prises de réglage ± 5 % à partir de 50 kVA
- Avec écran électrostatique

#### Primaire: 400 V - Secondaire: 400 V + N

■ Puissance: 16 kVA

- Borne primaire câble souple section : 35 mm²
- Borne secondaire câble souple section : 35 mm²

# Example of isolation transformer



KEL 8913-068-178MS-A-F SMD mounting Cable KEL8925-068-179-F

Layers G1 + GTL

**Signal Connectors** 

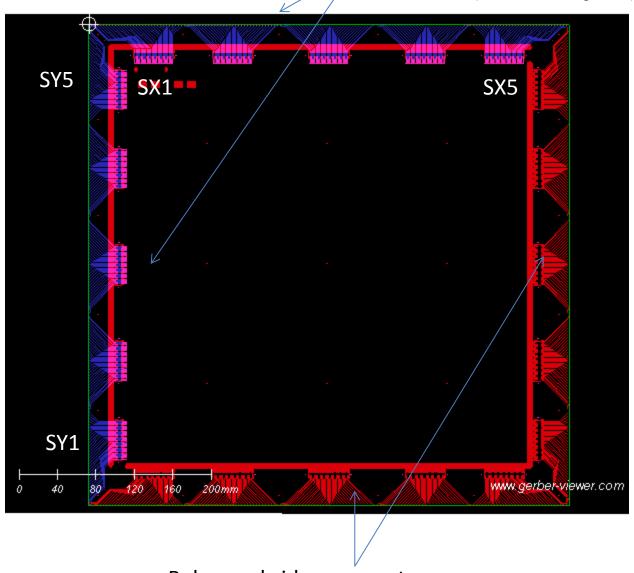
Connectors have the small hole at right and the large one at left, so the numbering of channels 1-32 proceeds in the same sense (small hole to large hole).

5 connectors of 32 channels per side:

SX1-5 Hor. SY1-5 Vert.

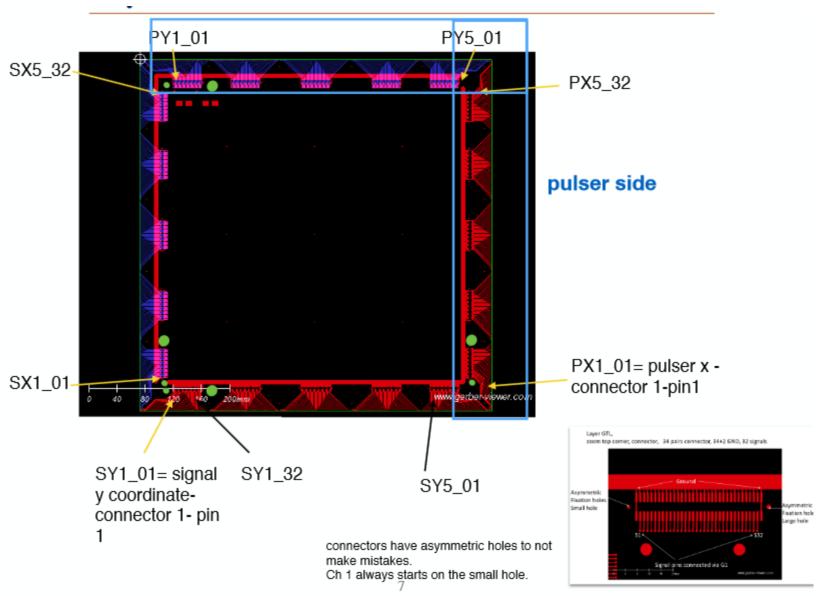
For more than one anode we just continue the counting in next anodes

For 3x1x1: SX1-SX20 SY1-SY10



Also the naming of connectors on a side will do the same from the side of the small hole SX1 –SX5

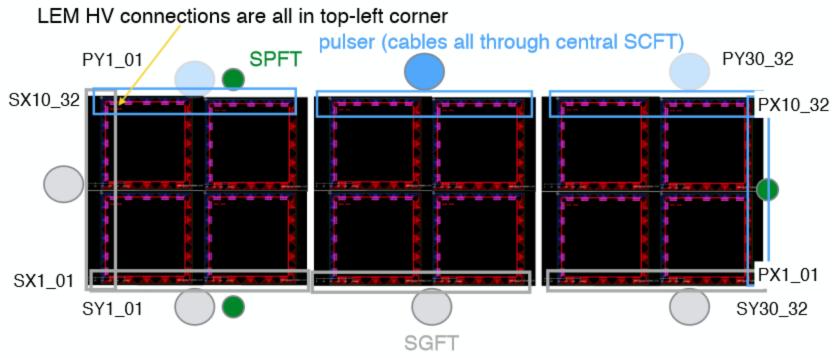
### 3x1x1 Meeting March 24th



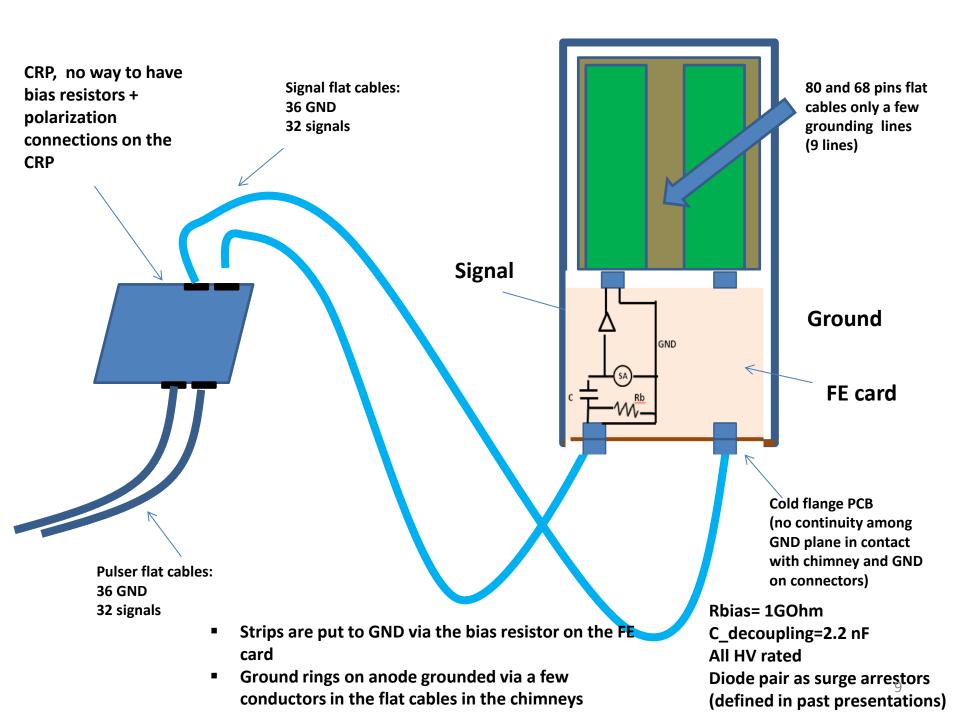
# 3x1x1 Meeting March 24th and last on April 28th

This is how the CRP will be mounted and LEM-HV cables cut to match this layout.

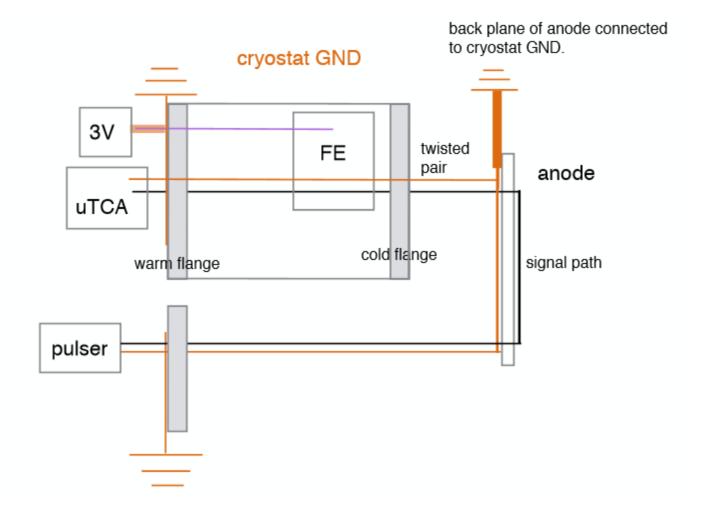
After next week- No going back!



- if we link the anode copper ground tracks as proposed in previous slide, then pulser/ signal have common GND
- 2. Do we agree on this layout and naming convention? (S,P)-(X,Y)-connector#\_pin#

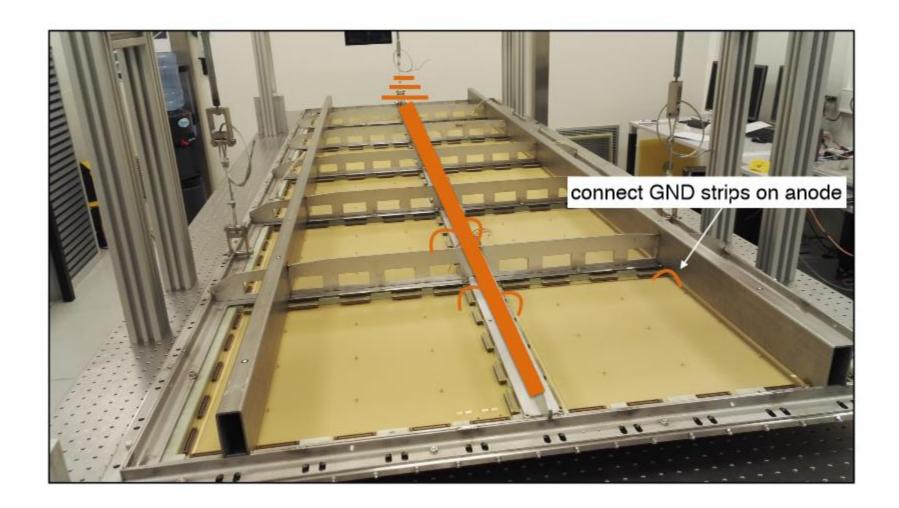


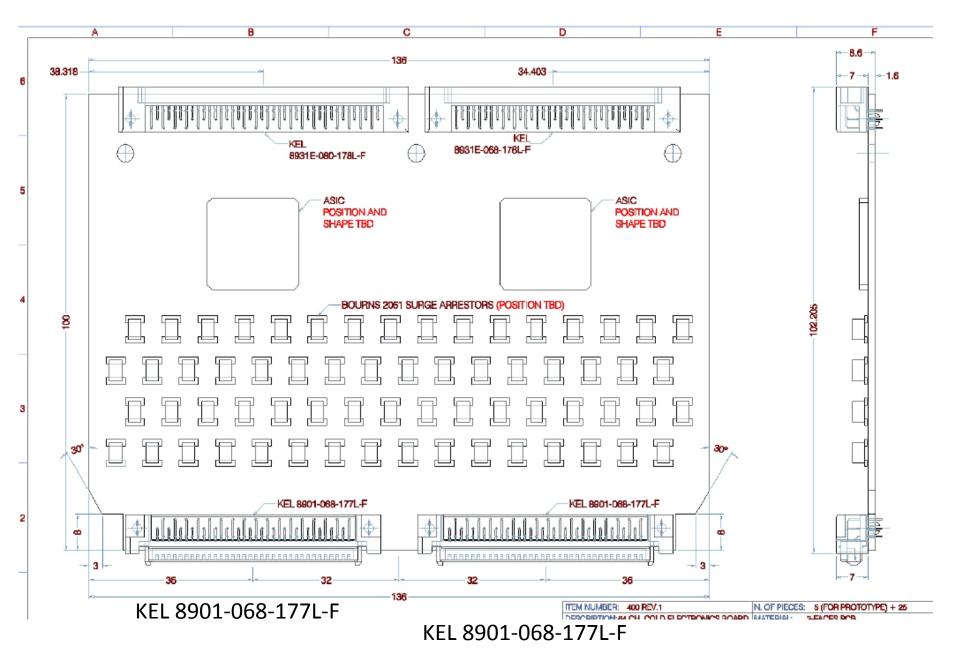
## 3x1x1 Meeting March 24th

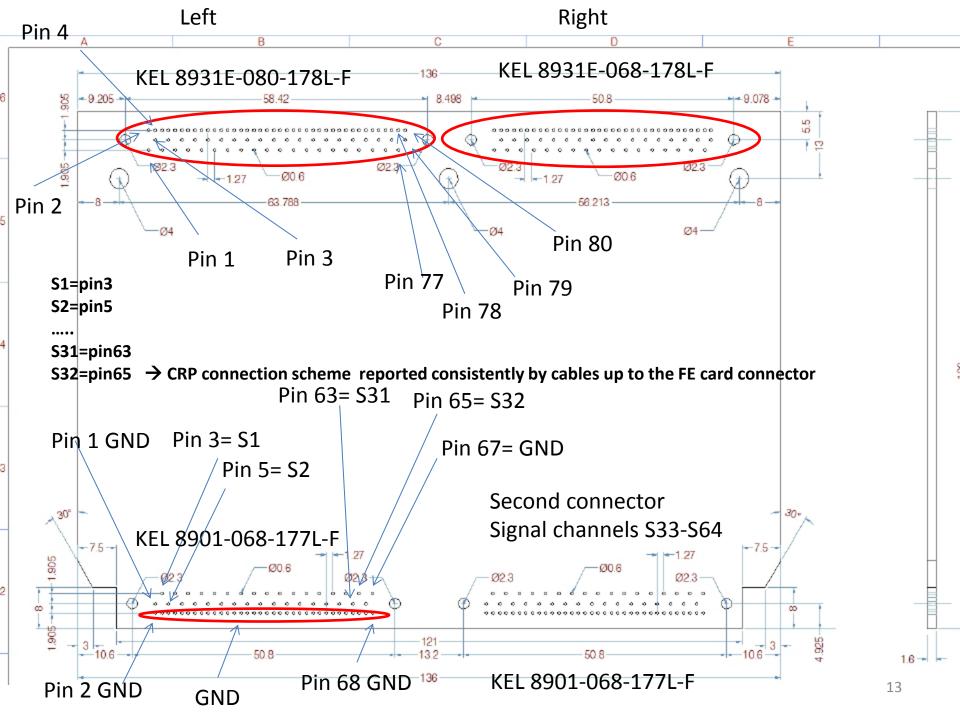




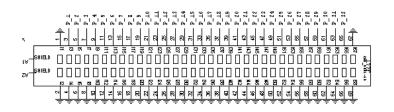
## **ETH** copper strip on CRP



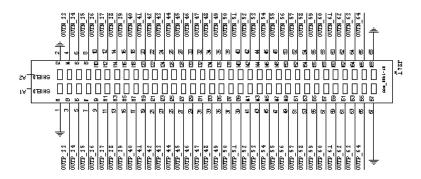


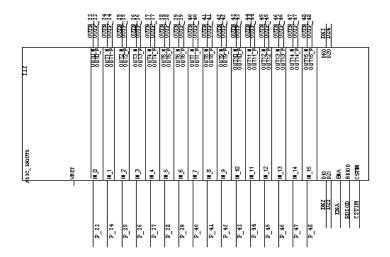


# Left **FE CARD** VBET | Color | Colo 扫描 TIN Teematin DX4 DZ1 EMA EDIOD CSTIM



### Right

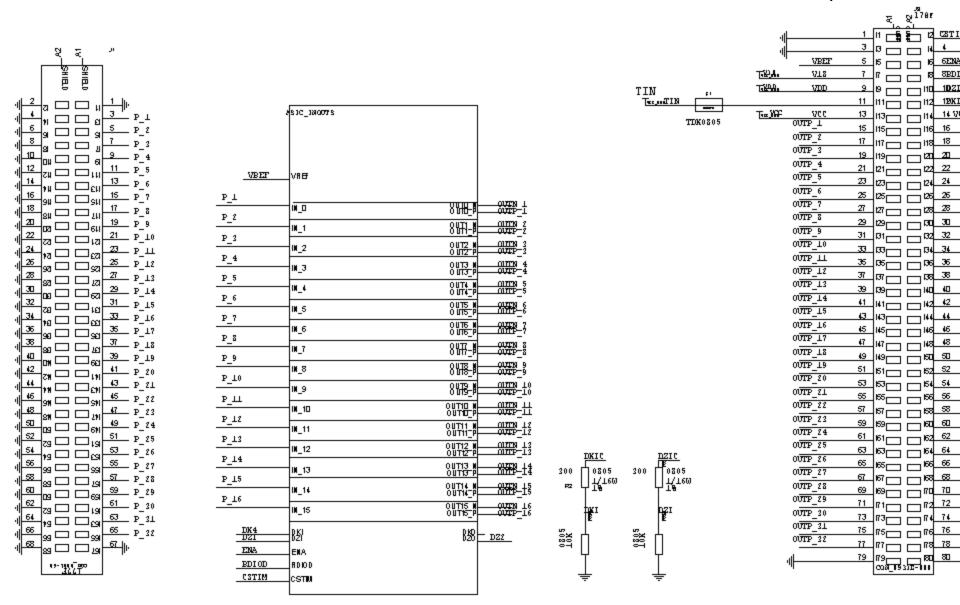




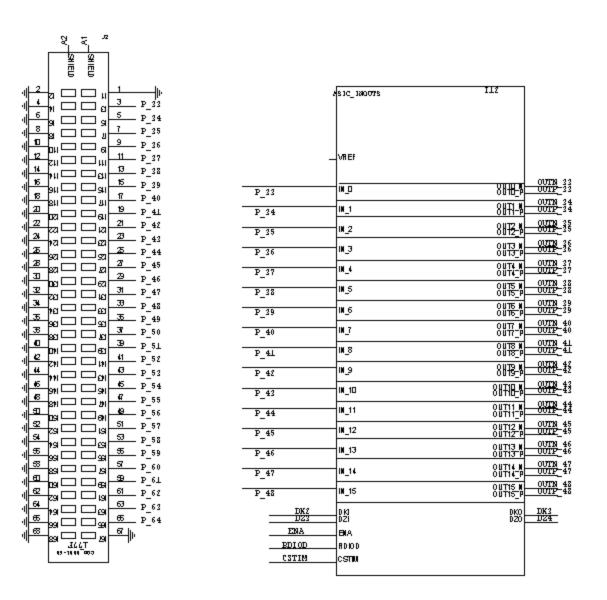


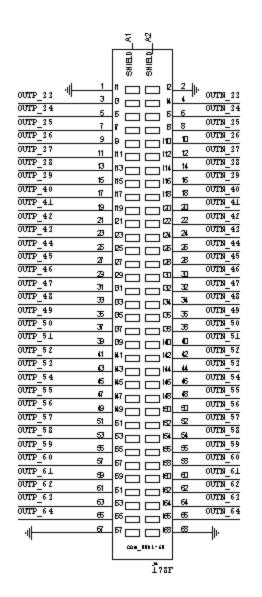
#### FE CARD

## LEFT $\rightarrow$ to 80 pins flat cable



Right  $\rightarrow$  to 68 pins flat cable





#### Pin assignments on 80 pins output connector of FE card

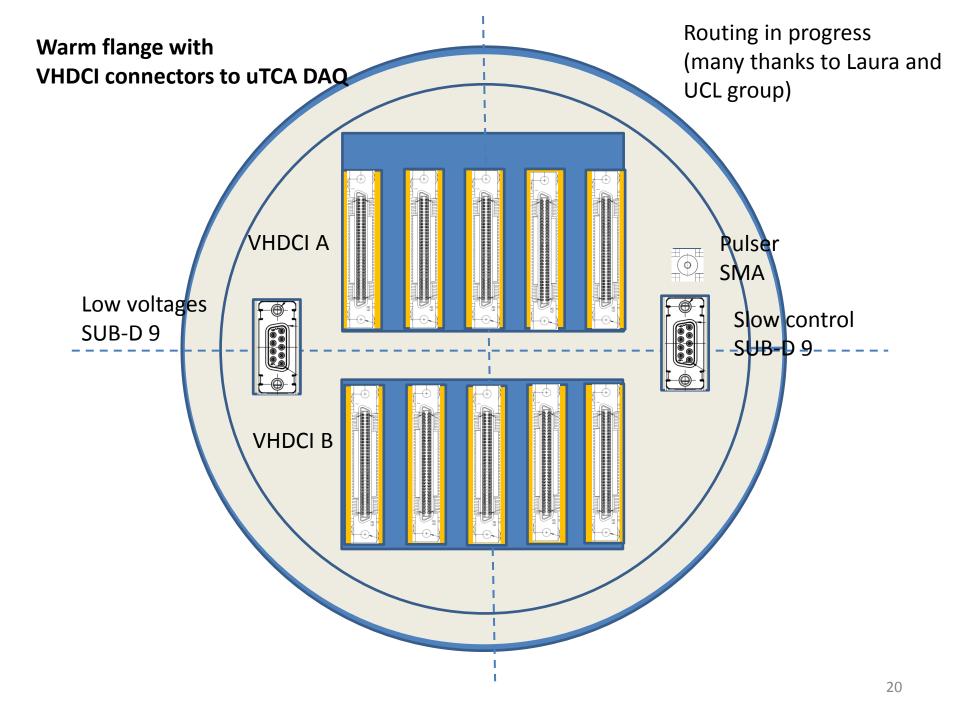
```
19 OUTP_3
1 GND
                                        20 OUTN_3
2 CSTIM (pulser)
3 GND
4 GND
5 VREF
           (Slow control, power block)
                                        75 OUTP_31
           Pins 1-14
6 ENA
                                        76 OUTN_31
7 V18
                                        77 OUTP_32
8 RDIOD
                                        78 OUTN 32
9 VDD
10 DZIC
                                        79 GND
11 TIN
                                        80 GND
12 DKIK
13 VCC
14 VCC
15 OUTP_1 differential out CH1
16 OUTN_1
17 OUTP 2
18 OUTN_2
```

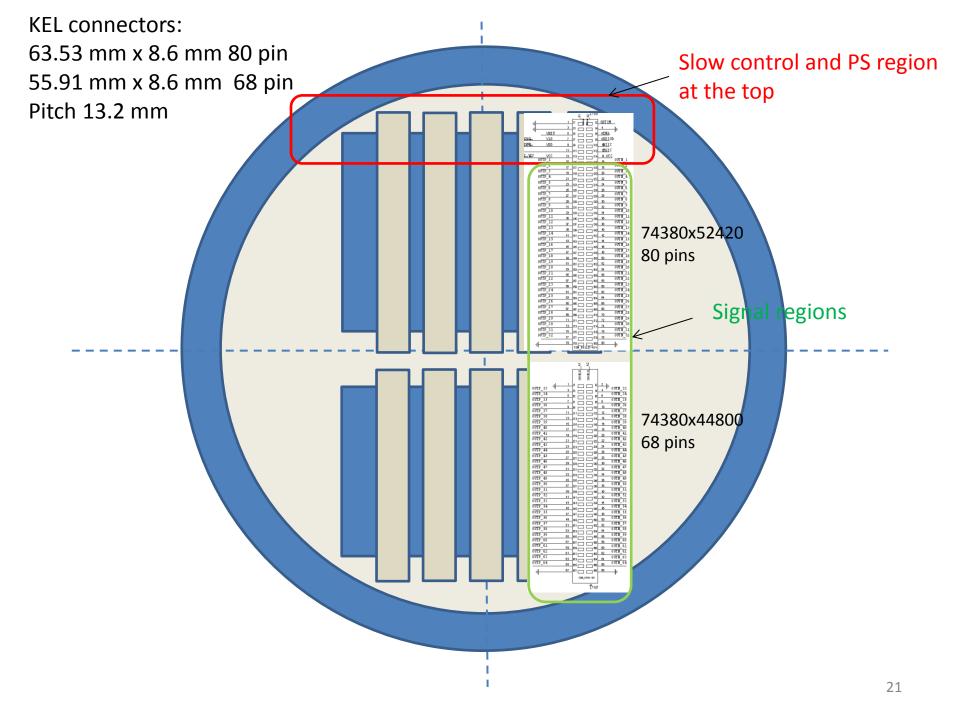
## Pin assignments on 68 pins output connector of FE card

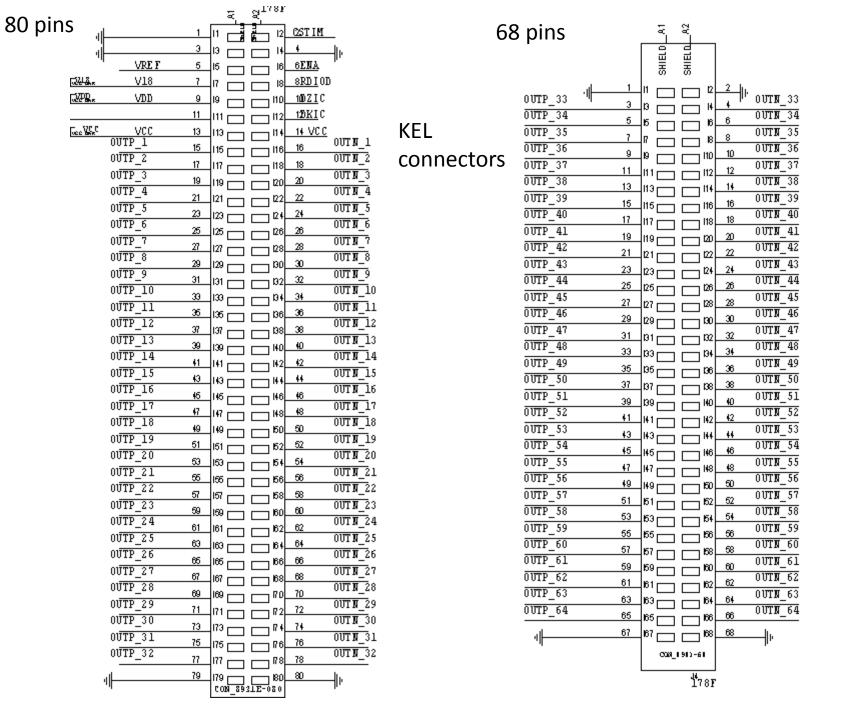
```
1 GND
2 GND
3 OUTP_33 differential out CH33
4 OUTN_33
5 OUTP_34
6 OUTN_34
•••••
63 OUTP_63
64 OUTN_63
65 OUTP_64
66 OUTN_64
67 GND
68 GND
```

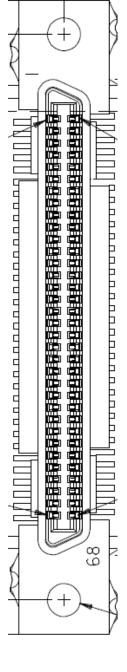
## **Summary of flat cable connectivity**

Pulser (80 pins flat cable):	5 Ground connections connector 80
2 CSTIM (pulser signal for charge injection for the	pins:
amplifier calibration), pulser connector should be	1 GND
connected to the GND plane too	3 GND
	4 GND
4 Controls (80 pins flat cable):	79 GND
6 ENA (Enable level: 0 or 3.3 V)	80 GND
8 RDIOD (Feedback comp. diode level: 0 or 3.3 V)	
10 DZIC (Slow control data spi-ʻlike')	4 Ground connections connector 68
12 DKIK (Slow control clock spi-'like')	pins:
	1 GND
6 Voltages (80 pins flat cable, fixed levels, provided by	2 GND
the filtered LV PS):	67 GND
5 VREF 1.4 V	68 GND
9 VDD 3.3 V	
7 V18 1.8 V	128 signal differential lines (+/-):
11 TIN 2.1 V	64 (80 pins connector) +64 (68 pins
13 VCC 3.3 V	connector) =128
14 VCC 3.3 V (duplicated line due to the current	,
consumption)	





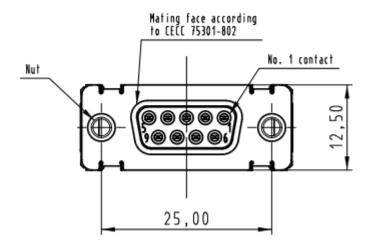




## Molex to uTCA crate (32 channels)

Pin		Pin	
1 S	1 P	35	S1 N
2 S	_ 2 P	36	S2 N
3 S	_ 3_P	37	S3_N
16 S	16_P	50	S16_N
17 G	IND	51	GND
18 G	IND	52	GND
19 S	17_P	53	S17_N
33 S	31_P	67	S31_N
34 S	32_P	68	S32_N
		_	

#### SUB-D9 Slow control

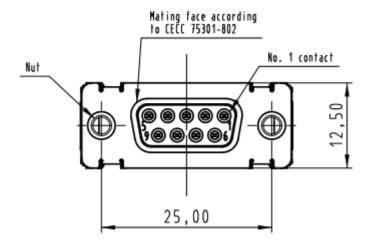


```
Pin1 → KEL80_6 ENA (Enable level: 0 or 3.3 V) (connector 1)
Pin2 → KEL80_6 ENA (Enable level: 0 or 3.3 V) (connector 2)
Pin 3→ KEL80_6 ENA (Enable level: 0 or 3.3 V) (connector 3)
Pin 4→ KEL80_6 ENA (Enable level: 0 or 3.3 V) (connector 4)
Pin 5→ KEL80_6 ENA (Enable level: 0 or 3.3 V) (connector 5)
Pin 6→ GND plane
Pin 7→ KEL80_8 RDIOD (Feedback comp. diode level: 0 or 3.3 V)
```

Connection in parallel To the 5 KEL80

Pin 7→KEL80\_8 RDIOD (Feedback comp. diode level: 0 or 3.3 V)
Pin8 →KEL80\_10 DZIC (Slow control data spi-'like')
Pin 9→KEL80\_12 DKIK (Slow control clock spi-'like')
Shield → GND plane

#### SUB-D9 Low voltages



Pin1  $\rightarrow$  KEL80\_5 VREF 1.4 V

Pin2 → KEL80 9 VDD 3.3 V

Pin3 → KEL80 7 V18 1.8 V

Pin4 → KEL80\_11 TIN 2.1 V

Pin5 → KEL80 13 VCC 3.3 V

Pin6 → KEL80\_14 VCC 3.3 V (duplicated line due to the current consumption)

Connection in parallel to the 5 KEL80

Pins7-9 → GND plane

Shield → GND plane

#### List of electrical equipments:

**Heinzinger HV PS for cathode:** ground defined by the cryostat by connecting the GND of the cable to the cryostat, ripple filter in series to the cable

**LEM HV PS:** similar to cathode HV PS

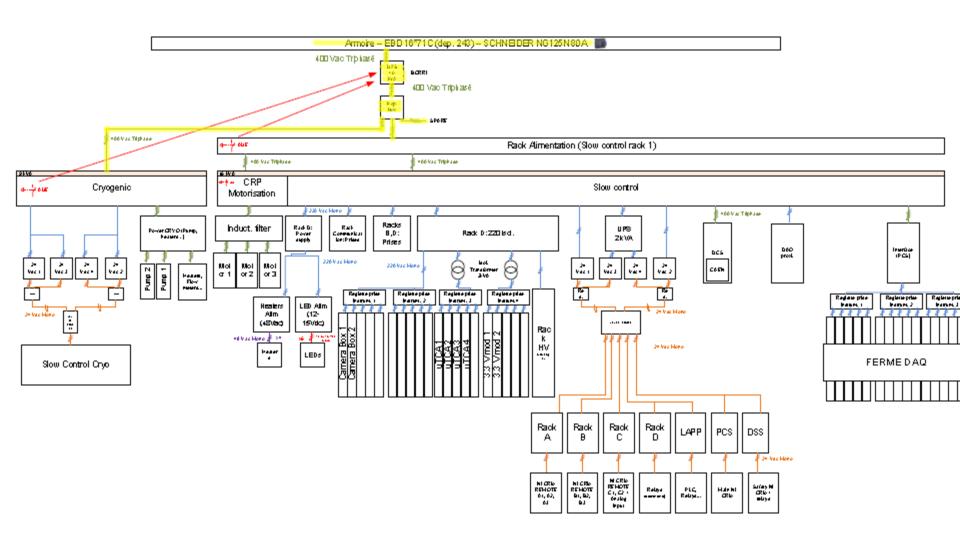
**Cold Electronics PS x2:** 230V, 350W, from dedicated multiplug isolation transformer to remove noise from other equipments connected to the same main, PS connected via shielded cables to chimneys patch boxes, GND and shield of the cables connected to cryostat

**uTCA crates x4:** 230V, 300 W from multiplug isolation transformer, ADC differential connections to patch box. GND defined via shield of the cables to the cryostat. ADC output via optical connections only. uTCA crate contains cards reading 64 ADCs each.

**Pulser:** pulser for calibrations of ASICS and strips, W from multiplug isolation transformer, 230V, 300W

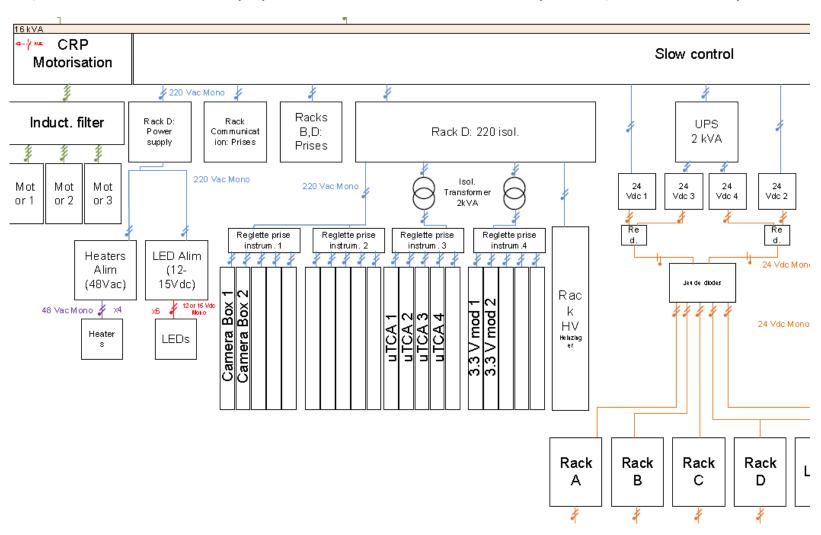
**Slow control equipments:** GND referred to cryostat

### Final scheme defined last Friday, under implementation by July 18th



Two separate isolation transformers:

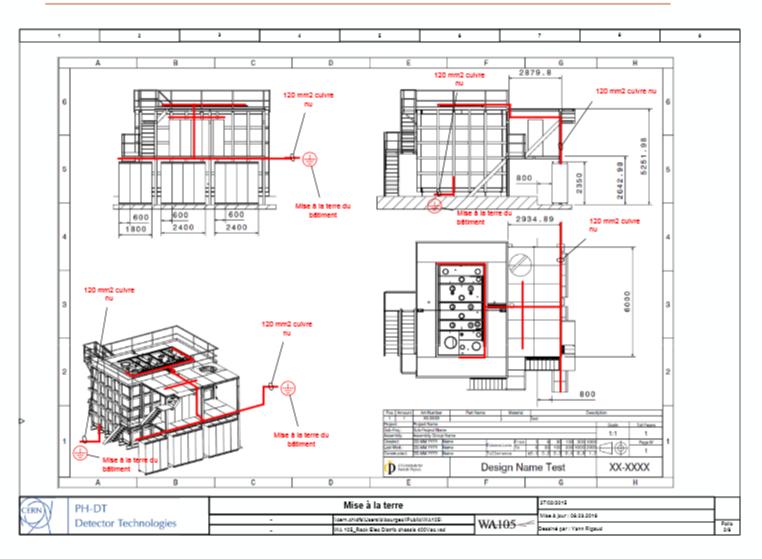
- a) For the LV PS (the most critical part of the system)
- b) For the other FE equipments on the roof of the cryostat (uTCA crates, pulser etc ..)



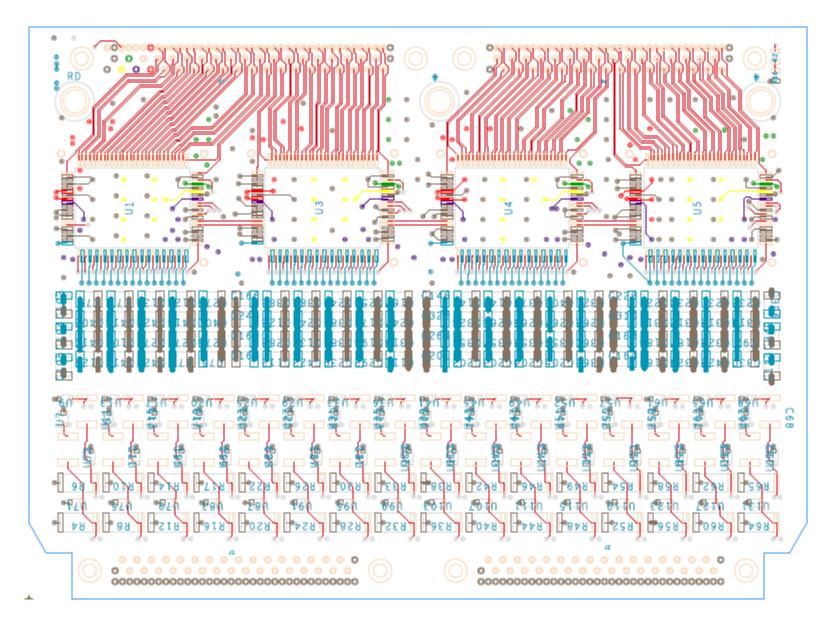


## **GND** copper layout scheme from Bourgeois

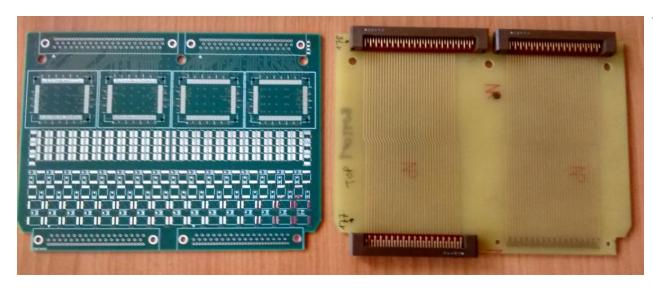




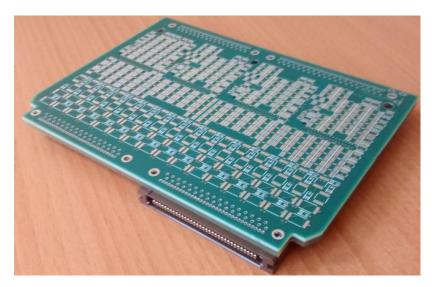
FE cards, already produced in a pre-batch for the 4 chimneys of 3x1

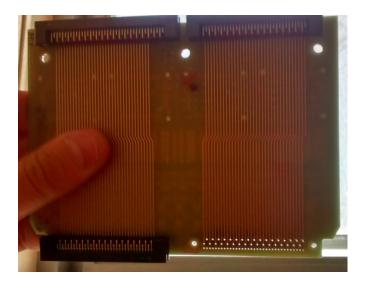


# The final FE card has extactly the same mechanical layout of the fake FE $\rightarrow$ no problems expected at the level of the insertion



The two layouts and all patterns of holes for the connectors correspond perfectly. When superimposing the two cards the connectors can be inserted with their pins easily crossing the two cards in a row and there is no difference on all the card borders.





## **Next tests:**

1) Week of June 20:

insertion tests of FE cards

check with diodes: small plug with a battery which uses one of the 9 GND lines and check the return of voltage on the other 8 GND lines by lighting diodes: the topology is such as the GND lines are always at the extremities of the connectors, so if they are in good contact the entire connector is well inserted

2)Possible continuity tests after moving the end-cap to the cryostat of all anodes (if anode pulser is functional) by using the fake FE cards → use of a small DAQ system (raspberry pi) with a relays switchbox to systematically acquire all the pulser waveforms on a digital scope

July4th: movement of the end-cap.

July 18th: grounding and electrical connections ready

3) After July 18<sup>th</sup>: Extensive noise tests of the FE electronics + grounding system after cryostat closure and grounding system implementation (in between July 18th and July 30th) → need the warm flange and grounding scheme in place